NST3906DP6T5G

Dual General Purpose Transistor

The NST3906DP6T5G device is a spin-off of our popular SOT-23/SOT-323/SOT-563 three-leaded device. It is designed for general purpose amplifier applications and is housed in the SOT-963 six-leaded surface mount package. By putting two discrete devices in one package, this device is ideal for low-power surface mount applications where board space is at a premium.

Features

- h_{FE}, 100–300
- Low $V_{CE(sat)} \le 0.4 \text{ V}$
- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- This is a Pb–Free Device

MAXIMUM RATINGS

Rating	Symbol	Value	Unit	
Collector – Emitter Voltage		V _{CEO}	-40	V
Collector – Base Voltage		V _{CBO}	-40	V
Emitter-Base Voltage		V _{EBO}	-5.0	V
Collector Current – Continuous		Ι _C	-200	mA
Electrostatic Discharge	HBM MM	ESD Class	2 B	

THERMAL CHARACTERISTICS

-			-
Characteristic (Single Heated)	Symbol	Max	Unit
Total Device Dissipation T _A = 25°C Derate above 25°C (Note 1)	P _D	240 1.9	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	R_{\thetaJA}	520	°C/W
Total Device Dissipation T _A = 25°C Derate above 25°C (Note 2)	P _D	280 2.2	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ hetaJA}$	446	°C/W
Characteristic (Dual Heated) (Note 3)	Symbol	Max	Unit
Total Device Dissipation T _A = 25°C	PD	350	mW
Derate above 25°C (Note 1)		2.8	mW/°C
Derate above 25°C (Note 1) Thermal Resistance, Junction-to-Ambient (Note 1)	R _{θJA}	2.8 357	mW/°C °C/W
Thermal Resistance, Junction-to-Ambient	R _{θJA} P _D		
Thermal Resistance, Junction-to-Ambient (Note 1) Total Device Dissipation $T_A = 25^{\circ}C$		357 420	°C/W mW
Thermal Resistance, Junction-to-Ambient (Note 1) Total Device Dissipation $T_A = 25^{\circ}C$ Derate above 25°C (Note 2) Thermal Resistance, Junction-to-Ambient	P _D	357 420 3.4	°C/W mW mW/°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-4 @ 100 mm², 1 oz. copper traces, still air. 2. FR-4 @ 500 mm², 1 oz. copper traces, still air.

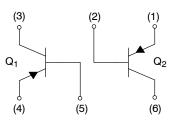
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3. Dual heated values assume total power is sum of two equally powered channels.



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NST3906DP6T5G







F = Device Code

= Date Code Μ

= Pb-Free Package •

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
NST3906DP6T5G	SOT-963 (Pb-Free)	8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

April, 2008 - Rev. 0

NST3906DP6T5G

ELECTRICAL CHARACTERISTICS (T_A = 25° C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector – Emitter Breakdown Voltage (Note 4) ($I_C = 1.0 \text{ mAdc}, I_B = 0$)	V _{(BR)CEO}	-40	-	V
Collector – Base Breakdown Voltage ($I_C = 10 \ \mu Adc$, $I_E = 0$)	V _{(BR)CBO}	-40	-	V
Emitter – Base Breakdown Voltage ($I_E = 10 \ \mu Adc$, $I_C = 0$)	V _{(BR)EBO}	-5.0	-	V
Collector Cutoff Current (V _{CE} = 30 Vdc, V _{EB} = 3.0 Vdc)	I _{CEX}	_	-50	nA

ON CHARACTERISTICS (Note 4)

DC Current Gain	h _{FE}			_
(I _C = -0.1 mA, V _{CE} = -1.0 V)		60	-	
(I _C = -1.0 mA, V _{CE} = -1.0 V)		80	-	
(I _C = -10 mA, V _{CE} = -1.0 V)		100	300	
(I _C = –50 mA, V _{CE} = –1.0 V)		60	-	
(I _C = -100 mA, V _{CE} = -1.0 V)		30	-	
Collector – Emitter Saturation Voltage	V _{CE(sat)}			V
(I _C = -10 mA, I _B = -1.0 mA)	()	-	-0.25	
(I _C = –50 mA, I _B = –5.0 mA)		-	-0.4	
Base – Emitter Saturation Voltage	V _{BE(sat)}			V
$(I_{\rm C} = -10 \text{ mA}, I_{\rm B} = -1.0 \text{ mA})$	()	-0.65	-0.85	
(I _C = –50 mA, I _B = –5.0 mA)		-	-0.95	

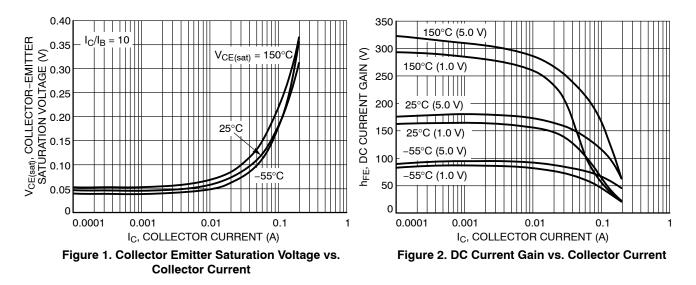
SMALL-SIGNAL CHARACTERISTICS

Current – Gain – Bandwidth Product (I_C = 10 mAdc, V_{CE} = 20 Vdc, f = 100 MHz)	f _T	250	-	MHz
Output Capacitance (V _{CB} = -5.0 V, I _E = 0 mA, f = 1.0 MHz)	C _{obo}	-	4.5	pF
Input Capacitance ($V_{EB} = -0.5 \text{ V}$, $I_E = 0 \text{ mA}$, f = 1.0 MHz)	C _{ibo}	-	10.0	pF
Noise Figure (V _{CE} = –5.0 V, I _C = –100 μ A, R _S = 1.0 k Ω , f = 1.0 kHz)	NF	_	4.0	dB

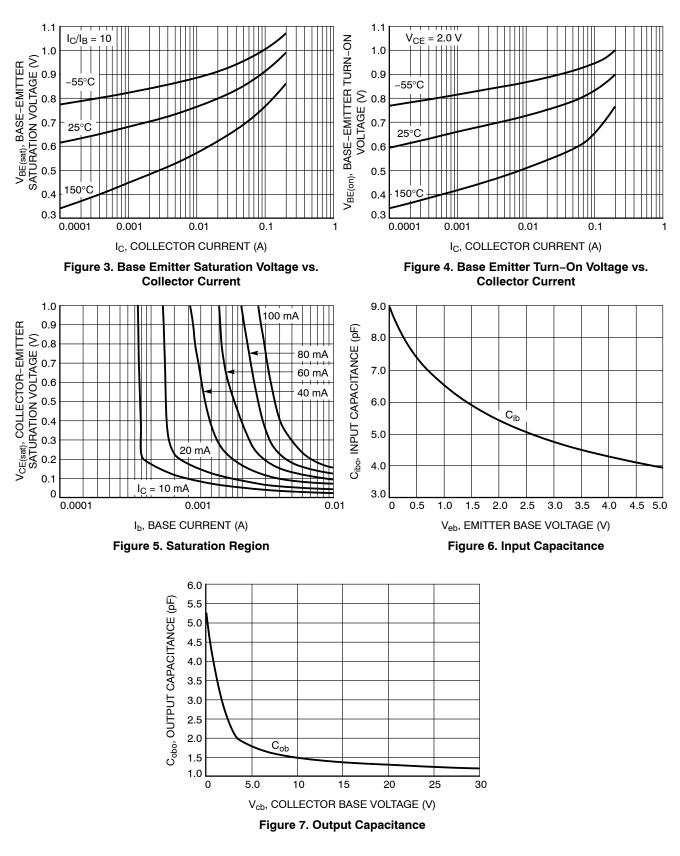
SWITCHING CHARACTERISTICS

Delay Time	$(V_{CC} = -3.0 \text{ V}, \text{ V}_{BE} = 0.5 \text{ V})$	t _d	-	35	
Rise Time	(I _C = -10 mA, I _{B1} = -1.0 mA)	t _r	-	35	ns
Storage Time	$(V_{CC} = -3.0 \text{ V}, I_C = -10 \text{ mA})$	t _s	-	250	20
Fall Time	(I _{B1} = I _{B2} = -1.0 mA)	t _f	-	50	ns

4. Pulse Test: Pulse Width \leq 300 μ s; Duty Cycle \leq 2.0%.

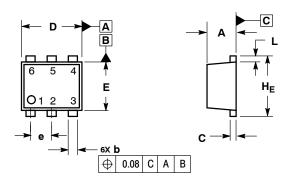


NST3906DP6T5G



PACKAGE DIMENSIONS

SOT-963 CASE 527AD-01 ISSUE B



NOTES: 1 DIMENSIONING AN

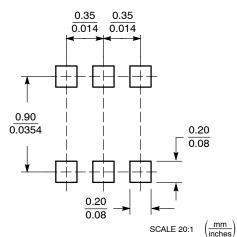
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

2. CONTROLLING DIMENSION: MILLIMETERS 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD

 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS		INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.34	0.37	0.40			
q	0.10	0.15	0.20	0.004	0.006	0.008
С	0.07	0.12	0.17	0.003	0.005	0.007
D	0.95	1.00	1.05	0.037	0.039	0.041
Е	0.75	0.80	0.85	0.03	0.032	0.034
е	e 0.35 BSC			().014 BS	iC
Г	0.05	0.10	0.15	0.002	0.004	0.006
ΗE	0.95	1.00	1.05	0.037	0.039	0.041

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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